

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT6225030

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
KATSUHIRO KITAGAWA	07/28/2020
YOSHIHITO MORISHITA	07/27/2020
DAIGO TOYAMA	07/27/2020
TAKAMASA SUZUKI	07/27/2020
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	MICRON TECHNOLOGY, INC.
<b>Street Address:</b>	8000 SOUTH FEDERAL WAY
<b>City:</b>	BOISE
<b>State/Country:</b>	IDAHO
<b>Postal Code:</b>	83716-9632
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16942503
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	206-903-8800
<b>Email:</b>	ip.docket.se@dorsey.com
<b>Correspondent Name:</b>	DORSEY & WHITNEY LLP-IP DEPT.-MTI
<b>Address Line 1:</b>	COLUMBIA CENTER
<b>Address Line 2:</b>	701 5TH AVENUE, SUITE 6100
<b>Address Line 4:</b>	SEATTLE, WASHINGTON 98104-7043
<b>ATTORNEY DOCKET NUMBER:</b>	P287468.US.01
<b>NAME OF SUBMITTER:</b>	YUNNY CHOI
<b>SIGNATURE:</b>	/Yunny Choi/
<b>DATE SIGNED:</b>	07/29/2020
<b>Total Attachments: 5</b>	
source=20200727_SignedAssignment_P287468US01#page1.tif	
source=20200727_SignedAssignment_P287468US01#page2.tif	

source=20200727\_SignedAssignment\_P287468US01#page3.tif  
source=20200727\_SignedAssignment\_P287468US01#page4.tif  
source=20200727\_SignedAssignment\_P287468US01#page5.tif

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Katsuhiro Kitagawa, Yoshihito  
Morishita, Daigo Toyama and Takamasa Suzuki

Filed : Concurrently herewith

For : APPARATUSES, SYSTEMS, AND  
METHODS FOR SYSTEM ON CHIP  
REPLACEMENT MODE

Docket No. P287468.US.01

Disclosure No. 2020-0388.00/US

ASSIGNMENT:

Enclosed for recording  
 Previously recorded

Date: \_\_\_\_\_

Reel: \_\_\_\_\_

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned does hereby:

SELL, ASSIGN AND TRANSFER to **Micron Technology, Inc.** (the "Assignee"), a corporation of Delaware, having a place of business at 8000 South Federal Way, Boise, Idaho 83716-9632, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith and is entitled "**APPARATUSES, SYSTEMS, AND METHODS FOR SYSTEM ON CHIP REPLACEMENT MODE**"; such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States of America;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee;

TO BE BINDING on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

Signature: Katsuhiro Kitagawa Date: 2020/7/28

Assignor Name: Katsuhiro Kitagawa

Signature: \_\_\_\_\_ Date: \_\_\_\_\_

Assignor Name: Yoshihito Morishita

Signature: \_\_\_\_\_ Date: \_\_\_\_\_

Assignor Name: Daigo Toyama

Signature: \_\_\_\_\_ Date: \_\_\_\_\_

Assignor Name: Takamasa Suzuki

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee;

TO BE BINDING on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Assignor Name: Katsuhiko Kitagawa

Signature:  \_\_\_\_\_

Date: 2020.09.29

Assignor Name: Yoshihito Morishita

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Assignor Name: Daigo Toyama

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Assignor Name: Takamasa Suzuki

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee;

TO BE BINDING on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

Signature: \_\_\_\_\_


Date: \_\_\_\_\_

Assignor Name: Katsuhiko Kitagawa

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Assignor Name: Yoshihito Morishita

Signature:  \_\_\_\_\_

Date: July 27, '20

Assignor Name: Daigo Toyama

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Assignor Name: Takamasa Suzuki

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee;

TO BE BINDING on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Assignor Name: Katsuhiko Kitagawa

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Assignor Name: Yoshihito Morishita

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Assignor Name: Daigo Toyama

Signature: Takamasa Suzuki

Date: 2020.7.27

Assignor Name: Takamasa Suzuki